

METHOD OF PROCESSING A SEMICONDUCTOR CHIP PACKAGE

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Abstract of the Disclosure

A method of removing dam bars (15) from leads (17) of a semiconductor chip package (10) is performed by first breaking a bond between the dam bars (15) and excess mold compound (12) from a mold compound (11). The bond is broken by slight movement of the dam bar (15). Thereafter, the dam bar (15) is completely removed by moving the dam bar (15) further, without causing chips or cracks in the mold compound (11).

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Fig. 1 accompanies this abstract.